National Semiconductor

T-46-07-11

MM54HC574/MM74HC574
TRI-STATE® Octal D-Type Edge-Triggered Flip-Flop

General Description

These high speed octal D-type flip-flops utilize advanced silicon-gate CMOS technology. They possess the high noise immunity and low power consumption of standard CMOS integrated circuits, as well as the ability to drive 15 LS-TTL loads. Due to the large output drive capability and the TRI-STATE feature, these devices are ideally suited for interfacing with bus lines in a bus organized system.

These devices are positive edge triggered flip-flops. Data at the D inputs, meeting the set-up and hold time requirements, are transferred to the Q outputs on positive going transitions of the CLOCK (CK) input. When a high logic level is applied to the OUTPUT CONTROL (OC) input, all outputs go to a high impedance state, regardless of what signals are present at the other inputs and the state of the storage elements.

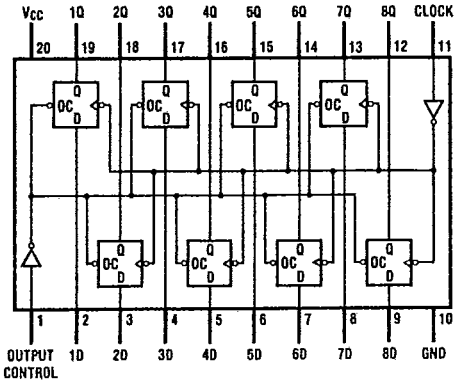
The 54HC/74HC logic family is speed, function, and pinout compatible with the standard 54LS/74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to V_{CC} and ground.

Features

- Typical propagation delay: 13 ns
- Wide operating voltage range: 2V–6V
- Low input current: 1 μA maximum
- Low quiescent current: 80 μA maximum
- Compatible with bus-oriented systems
- Output drive capability: 15 LS-TTL loads

Connection Diagram

Dual-In-Line Package



TL/F/5213–1

Top View

Order Number MM54HC574* or MM74HC574*

*Please look into Section 8, Appendix D for availability of various package types.

Truth Table

Output Control	Clock	Data	Output
L	↑	H	H
L	↑	L	L
L	L	X	Q_0
H	X	X	Z

H = high level, L = low level
X = don't care
↑ = transition from low-to-high
Z = high impedance state
Q_0 = the level of the output before steady state input conditions were established

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Absolute Maximum Ratings (Notes 1 & 2)

If Military/Aerospace specified devices are required, contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Supply Voltage (V_{CC})	−0.5 to +7.0V
DC Input Voltage (V_{IN})	−1.5 to V_{CC}+1.5V
DC Output Voltage (V_{OUT})	−0.5 to V_{CC}+0.5V
Clamp Diode Current (I_{IK}, I_{OK})	±20 mA
DC Output Current, per pin (I_{OUT})	±35 mA
DC V_{CC} or GND Current, per pin (I_{CC})	±70 mA
Storage Temperature Range (T_{STG})	−65°C to +150°C
Power Dissipation (P_D) (Note 3)	600 mW
S.O. Package only	500 mW
Lead Temperature (T_L) (Soldering 10 seconds)	260°C

Operating Conditions

	Min	Max	Units
Supply Voltage (V_{CC})	2	6	V
DC Input or Output Voltage (V_{IN},V_{OUT})	0	V_{CC}	V
Operating Temp. Range (T_A)			
MM74HC	−40	+85	°C
MM54HC	−55	+125	°C
Input Rise or Fall Times (t_r, t_f) V_{CC}=2.0V		1000	ns
V_{CC}=4.5V		500	ns
V_{CC}=6.0V		400	ns

DC Electrical Characteristics (Note 4)

Symbol	Parameter	Conditions	V_{CC}	T_A=25°C	74HC T_A=−40 to 85°C	54HC T_A=−55 to 125°C	Units
				Typ	Guaranteed Limits		
V_{IH}	Minimum High Level Input Voltage		2.0V		1.5	1.5	1.5	V
			4.5V		3.15	3.15	3.15	V
			6.0V		4.2	4.2	4.2	V
V_{IL}	Maximum Low Level Input Voltage**		2.0V		0.5	0.5	0.5	V
			4.5V		1.35	1.35	1.35	V
			6.0V		1.8	1.8	1.8	V
V_{OH}	Minimum High Level Output Voltage	V_{IN}=V_{IH} or V_{IL} $\|I_{OUT}\|$≤20 μA	2.0V	2.0	1.9	1.9	1.9	V
			4.5V	4.5	4.4	4.4	4.4	V
			6.0V	6.0	5.9	5.9	5.9	V
		V_{IN}=V_{IH} or V_{IL} $\|I_{OUT}\|$≤6.0 mA	4.5V	4.2	3.98	3.84	3.7	V
		$\|I_{OUT}\|$≤7.8 mA	6.0V	5.7	5.48	5.34	5.2	V
V_{OL}	Maximum Low Level Output Voltage	V_{IN}=V_{IH} or V_{IL} $\|I_{OUT}\|$≤20 μA	2.0V	0	0.1	0.1	0.1	V
			4.5V	0	0.1	0.1	0.1	V
			6.0V	0	0.1	0.1	0.1	V
		V_{IN}=V_{IH} or V_{IL} $\|I_{OUT}\|$≤6.0 mA	4.5V	0.2	0.26	0.33	0.4	V
		$\|I_{OUT}\|$≤7.8 mA	6.0V	0.2	0.26	0.33	0.4	V
I_{IN}	Maximum Input Current	V_{IN}=V_{CC} or GND	6.0V		±0.1	±1.0	±1.0	μA
I_{OZ}	Maximum TRI-STATE Output Leakage Current	V_{OUT}=V_{CC} or GND	6.0V		±0.5	±5.0	±10	μA
I_{CC}	Maximum Quiescent Supply Current	V_{IN}=V_{CC} or GND I_{OUT}=0 μA	6.0V		8.0	80	160	μA

Note 1: Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 3: Power Dissipation temperature derating — plastic "N" package: −12 mW/°C from 65°C to 85°C; ceramic "J" package: −12 mW/°C from 100°C to 125°C.

Note 4: For a power supply of 5V ±10% the worst-case output voltages (V_{OH}, and V_{OL}) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst-case V_{IH} and V_{IL} occur at V_{CC}=5.5V and 4.5V respectively. (The V_{IH} value at 5.5V is 3.85V.) The worst-case leakage current (I_{IN}, I_{CC}, and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0V values should be used.

**V_{IL} limits are currently tested at 20% of V_{CC}. The above V_{IL} specification (30% of V_{CC}) will be implemented no later than Q1, CY'89.

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AC Electrical Characteristics $V_{CC}=5V$, $T_A=25°C$, $t_r=t_f=6$ ns

Symbol	Parameter	Conditions	Typ	Guaranteed Limit	Units
f_{MAX}	Maximum Operating Frequency		50	35	MHz
t_{PHL}, t_{PLH}	Maximum Propagation Delay, Clock to Q	$C_L=45$ pF	12	20	ns
t_{PZH}, t_{PZL}	Maximum Output Enable Time	$R_L=1$ kΩ $C_L=45$ pF	13	25	ns
t_{PHZ}, t_{PLZ}	Maximum Output Disable Time	$R_L=1$ kΩ $C_L=5$ pF	11	20	ns
t_S	Minimum Setup Time, Data to Clock		10	20	ns
t_H	Minimum Hold Time, Clock to Data		−3	0	ns
t_W	Minimum Pulse Clock Width		8	16	ns

AC Electrical Characteristics $V_{CC}=2.0$–$6.0V$, $C_L=50$ pF, $t_r=t_f=6$ ns (unless otherwise specified)

Symbol	Parameter	Conditions	V_{CC}	$T_A=25°C$	74HC $T_A=-40$ to $85°C$	54HC $T_A=-55$ to $125°C$	Units
				Typ	Guaranteed Limits		
f_{MAX}	Maximum Operating Frequency	$C_L=50$ pF	2.0V		6	5	4	MHz
			4.5V		30	24	20	MHz
			6.0V		35	28	23	MHz
t_{PHL}, t_{PLH}	Maximum Propagation Delay, Clock to Q	$C_L=50$ pF	2.0V	40	115	143	173	ns
		$C_L=150$ pF	2.0V	51	155	194	233	ns
		$C_L=50$ pF	4.5V	13	23	29	35	ns
		$C_L=150$ pF	4.5V	19	31	47	47	ns
		$C_L=50$ pF	6.0V	12	20	25	30	ns
		$C_L=150$ pF	6.0V	18	27	34	41	ns
t_{PZH}, t_{PZL}	Maximum Output Enable Time	$R_L=1$ kΩ $C_L=50$ pF	2.0V	45	140	175	210	ns
		$C_L=150$ pF	2.0V	59	180	225	270	ns
		$C_L=50$ pF	4.5V	14	28	35	42	ns
		$C_L=150$ pF	4.5V	20	36	45	54	ns
		$C_L=50$ pF	6.0V	12	24	30	36	ns
		$C_L=150$ pF	6.0V	18	31	39	47	ns
t_{PHZ}, t_{PLZ}	Maximum Output Disable Time	$R_L=1$ kΩ $C_L=50$ pF	2.0V	35	125	156	188	ns
			4.5V	12	25	31	38	ns
			6.0V	10	21	27	32	ns
t_S	Minimum Setup Time Data to Clock		2.0V		100	125	150	ns
			4.5V		20	25	30	ns
			6.0V		17	21	25	ns
t_H	Minimum Hold Time Clock to Data		2.0V		0	0	0	ns
			4.5V		0	0	0	ns
			6.0V		0	0	0	ns
t_{THL}, t_{TLH}	Maximum Output Rise and Fall Time	$C_L=50$ pF	2.0V	25	60	75	90	ns
			4.5V	7	12	15	18	ns
			6.0V	6	10	13	15	ns
t_W	Minimum Clock Pulse Width		2.0V	30	80	100	120	ns
			4.5V	9	16	20	24	ns
			6.0V	8	14	18	20	ns
t_r, t_f	Maximum Clock Input Rise and Fall Time		2.0V		1000	1000	1000	ns
			4.5V		500	500	500	ns
			6.0V		400	400	400	ns
C_{PD}	Power Dissipation Capacitance (Note 5) (per latch)	OC=VCC		30				pF
		OC=GND		50				pF
C_{IN}	Maximum Input Capacitance			5	10	10	10	pF
C_{OUT}	Maximum Output Capacitance			15	20	20	20	pF

Note 5: C_{PD} determines the no load dynamic power consumption, $P_D=C_{PD}V_{CC}^2f+I_{CC}V_{CC}$, and the no load dynamic current consumption, $I_S=C_{PD}V_{CC}f+I_{CC}$.

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